EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	158	boundary scan and scan chain and IP	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	ADJ	ON	2007/12/17 18:47
L2	5158	(internal or boundary) scan	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2007/12/17 18:47
L3	1	(US-20040195672-$).did.	US-PGPUB	OR	OFF	2007/12/17 18:47
L4	1	L2 and L3	US-PGPUB; USPAT	OR	OFF	2007/12/17 18:47
L5	16	(US-20020194564-$ or US-20030006795-$ or US-20030032263-$ or US-20040195672-$ or US-20040197941-$ or US-20040199840-$ or US-20040221143-$).did. or (US-6094736-$ or US-4728751-$ or US-5673276-$ or US-6263422-$ or US-6237054-$ or US-6330666-$ or US-5383192-$ or US-5341096-$ or US-6734549-$).did.	US-PGPUB; USPAT	OR	OFF	2007/12/17 18:47
L6	242	internal scan same boundary scan	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2007/12/17 18:47
L7	1	L6 and L3	US-PGPUB; USPAT	OR	OFF	2007/12/17 18:47
L8	10	(US-20030032263-$ or US-20030006795-$ or US-20020194564-$ or US-20040195672-$).did. or (US-6237054-$ or US-5341096-$ or US-4728751-$ or US-6094736-$ or US-6263422-$ or US-5673276-$).did.	US-PGPUB; USPAT	OR	OFF	2007/12/17 18:47
L9	7	L8 and device with test$3	US-PGPUB; USPAT	OR	ON	2007/12/17 18:47
L10	1394	(257/48).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/12/17 18:47

L11	54	interface with two-wire adj type	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2007/12/17 18:47
L12	43	L11 and (test tested testing tester test adj frame)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2007/12/17 18:47
L13	1313	boundary scan test	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/12/17 18:47
L14	3589	(714/724,726,727).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/12/17 18:47
L15	385	L13 and L14	US-PGPUB; USPAT; USOCR	ADJ	OFF	2007/12/17 18:47
L16	117	L1 and (silicon semiconductor gaas inp)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2007/12/17 18:47
L17	117	L16 and (test tested testing tester test adj frame)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2007/12/17 18:47
L18	154	L13 and internal scan	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/12/17 18:47
L19	23	L13 and internal scan chain	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/12/17 18:47
L20	19	L19 and (board pcb mount mounting substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/17 18:47

L21	12	L20 and (wire wiring bond bonding)	US-PGPUB; USPAT; USOCR	OR	ON	2007/12/17 18:47
L22	139	L18 and (board pcb mount mounting substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/17 18:47
L23	109	L22 and (wire wiring bond bonding)	US-PGPUB; USPAT; USOCR	OR	ON	2007/12/17 18:47
L24	89	chip adj IP and IP	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2007/12/17 18:47
L25	9	L21 and input terminal and output terminal	US-PGPUB; USPAT; USOCR	ADJ	ON	2007/12/17 18:47
L26	3	L8 and (DUT device adj2 test)	US-PGPUB; USPAT	OR	OFF	2007/12/17 18:47
L27	2003	(multi-chip package or MCP or multi-chip module or MCM) near3 (semiconductor or silicon)	US-PGPUB; USPAT; USOCR	ADJ	ON	2007/12/17 18:47
L28	92	L23 and chip	US-PGPUB; USPAT; USOCR	OR	ON	2007/12/17 18:47
L29	21	IP Super-Sub	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	ADJ	ON	2007/12/17 18:47
L30	24	(silicon semiconductor) same ceramic same (submount mount) same (TCE thermal adj coefficient)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2007/12/17 18:47
L31	3	L8 and under with test$3	US-PGPUB; USPAT	OR	ON	2007/12/17 18:47
L32	59	chip adj IP and IP and intellectual adj property	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2007/12/17 18:47
L33	13	scan chain and L27	US-PGPUB; USPAT; USOCR	ADJ	ON	2007/12/17 18:47

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L34	29	boundary scan and L27	US-PGPUB; USPAT; USOCR	ADJ	ON	2007/12/17 18:47
L35	1	(US-6734549-$).did.	USPAT	OR	OFF	2007/12/17 19:10
L36	1	35 and boundary with internal	USPAT	OR	OFF	2007/12/17 19:10
L37	1	35 and boundary with internal.detx.	USPAT	OR	OFF	2007/12/17 19:10